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September 2001

## FQA28N50F

#### 500V N-Channel MOSFET

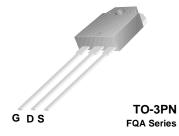
#### **General Description**

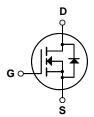
These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switch mode power supplies, where the body diode is used such as phase-shift ZVS, basic full-bridge topology.

#### **Features**

- 28.4A, 500V,  $R_{DS(on)}$  = 0.16 $\Omega$  @V<sub>GS</sub> = 10 V Low gate charge ( typical 110 nC)
- Low Crss (typical 60 pF)
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability
- Fast recovery body diode (max, 250ns)





## Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted

Symbol	Parameter		FQA28N50F	Units
V <sub>DSS</sub>	Drain-Source Voltage		500	V
I <sub>D</sub>	Drain Current - Continuous (T <sub>C</sub> = 25°	C)	28.4	А
	- Continuous (T <sub>C</sub> = 100	0°C)	18	А
I <sub>DM</sub>	Drain Current - Pulsed	(Note 1)	113.6	А
V <sub>GSS</sub>	Gate-Source Voltage		± 30	V
E <sub>AS</sub>	Single Pulsed Avalanche Energy	(Note 2)	1300	mJ
I <sub>AR</sub>	Avalanche Current	(Note 1)	28.4	А
E <sub>AR</sub>	Repetitive Avalanche Energy	(Note 1)	31	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	17	V/ns
$P_{D}$	Power Dissipation (T <sub>C</sub> = 25°C)		310	W
	- Derate above 25°C		2.5	W/°C
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range		-55 to +150	°C
T <sub>L</sub>	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300	°C

### **Thermal Characteristics**

Symbol	Parameter	Тур	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		0.4	°C/W
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink	0.24		°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		40	°C/W

Symbol	Parameter	Test Conditions		Min	Тур	Max	Units
Off Cha	aracteristics						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		500			V
ΔBV <sub>DSS</sub> / ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	$I_D = 250 \mu\text{A}$ , Referenced to	25°C		0.5		V/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 500 V, V <sub>GS</sub> = 0 V				50	μΑ
		V <sub>DS</sub> = 400 V, T <sub>C</sub> = 125°C				500	μΑ
I <sub>GSSF</sub>	Gate-Body Leakage Current, Forward	V <sub>GS</sub> = 30 V, V <sub>DS</sub> = 0 V				100	nA
I <sub>GSSR</sub>	Gate-Body Leakage Current, Reverse	$V_{GS} = -30 \text{ V}, V_{DS} = 0 \text{ V}$				-100	nA
On Cha	racteristics						
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$		3.0		5.0	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 14.2 A			0.126	0.16	Ω
9 <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 50 V, I <sub>D</sub> = 14.2 A	(Note 4)		28		S
C <sub>iss</sub> C <sub>oss</sub> C <sub>rss</sub>	Input Capacitance Output Capacitance Reverse Transfer Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1.0 MHz		  	4300 640 60	5600 830 80	pF pF
	ing Characteristics						
t <sub>d(on)</sub>	Turn-On Delay Time	$V_{DD} = 250 \text{ V}, I_{D} = 28.4 \text{ A},$ $R_{G} = 25 \Omega$			100	210	ns
t <sub>r</sub>	Turn-On Rise Time				290	590	ns
t <sub>d(off)</sub>	Turn-Off Delay Time				250	510	ns
t <sub>f</sub>	Turn-Off Fall Time	(1)	lote 4, 5)		175	360	ns
Qg	Total Gate Charge	V <sub>DS</sub> = 400 V, I <sub>D</sub> = 28.4 A,			110	140	nC
Q <sub>gs</sub>	Gate-Source Charge	V <sub>GS</sub> = 10 V (Note 4, 5)			32		nC
Q <sub>gd</sub>	Gate-Drain Charge				59		nC
Drain-S	Source Diode Characteristics a	nd Maximum Ratings					
I <sub>S</sub>	Maximum Continuous Drain-Source Diode Forward Current					28.4	Α
I <sub>SM</sub>	Maximum Pulsed Drain-Source Diode F	Forward Current				113.6	Α
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 28.4 \text{ A}$				1.4	V
t <sub>rr</sub>	Reverse Recovery Time	$V_{GS} = 0 \text{ V}, I_S = 28.4 \text{ A},$				250	ns
Q <sub>rr</sub>	Reverse Recovery Charge	dl <sub>F</sub> / dt = 100 A/μs	(Note 4)		1.2		μС

- **Notes:**1. Repetitive Rating : Pulse width limited by maximum junction temperature 2. L = 2.9mH, I<sub>AS</sub> = 28.4A, V<sub>DD</sub> = 50V, R<sub>G</sub> = 25  $\Omega$ , Starting T<sub>J</sub> = 25°C 3. I<sub>SD</sub>  $\leq$  28.4A, di/dt  $\leq$  350 $\Lambda$ / $\mu$ s, V<sub>DD</sub>  $\leq$  BV<sub>DSS</sub>, Starting T<sub>J</sub> = 25°C 4. Pulse Test : Pulse width  $\leq$  300 $\mu$ s, Duty cycle  $\leq$  2% 5. Essentially independent of operating temperature

## **Typical Characteristics**

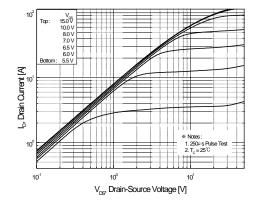


Figure 1. On-Region Characteristics

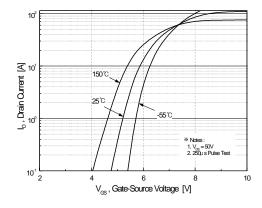


Figure 2. Transfer Characteristics

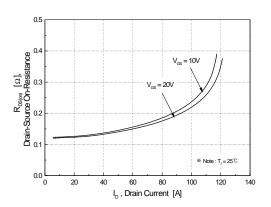


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

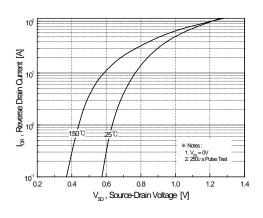


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

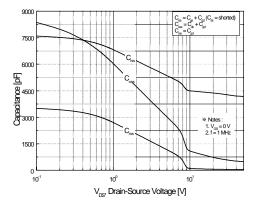


Figure 5. Capacitance Characteristics

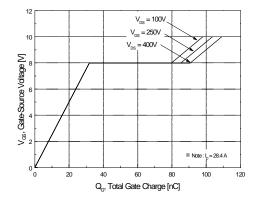


Figure 6. Gate Charge Characteristics



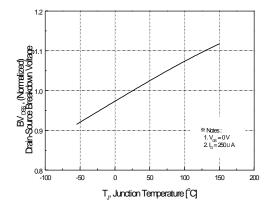
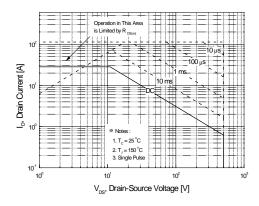


Figure 7. Breakdown Voltage Variation vs Temperature





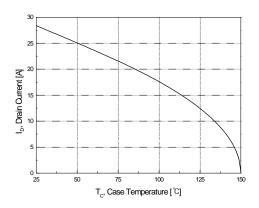


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs Case Temperature

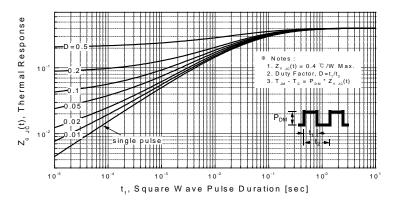
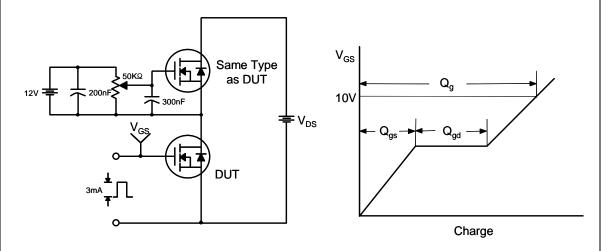


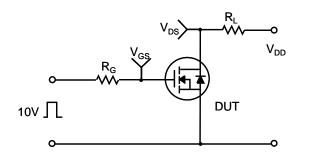
Figure 11. Transient Thermal Response Curve

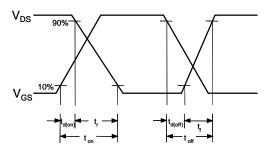
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### **Gate Charge Test Circuit & Waveform**

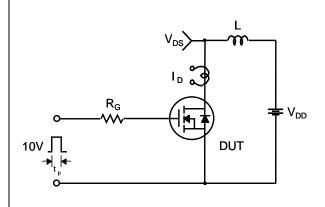


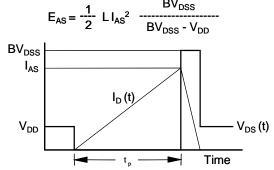
#### **Resistive Switching Test Circuit & Waveforms**



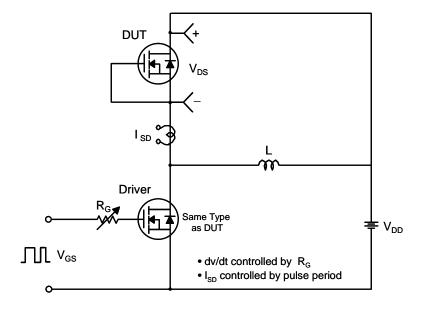


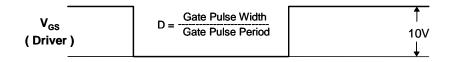
### **Unclamped Inductive Switching Test Circuit & Waveforms**

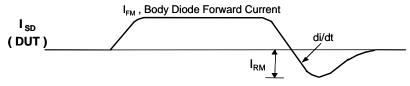




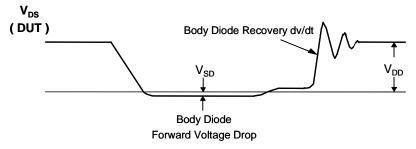
#### Peak Diode Recovery dv/dt Test Circuit & Waveforms





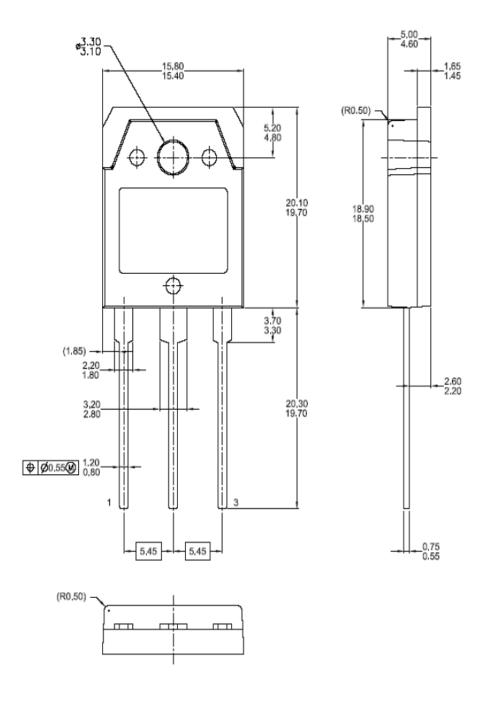


Body Diode Reverse Current





TO-3PN



Dimensions in Millimeters

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